



## Final Product Change Notification

202008033F01

**Issue Date:** 02-Sep-2020  
**Effective Date:** 30-Nov-2020

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# QUALITY

### Management Summary

Cu Wire is being added as a wirebond material option for LPC236x and LPC24xx in TFBGA100, TFBGA180 and TFBGA208 packages at assembly site NXP-ATKH.

### Change Category

- |  |  |   |   |   |
|--|--|---|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input checked="" type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification   | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling  | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |   |   |   |

LPC236x, LPC24xx in TFBGA100, 180, 208 Package Cu Wire Qualification for NXP-ATKH

### Description of Change

Copper wire has been qualified and will be added as a wirebond material. Upon effective date, NXP will begin shipping product with copper wire.

Mold compound has been upgraded to support copper wire.

See attached Self Qualification Report (SQR) for details of the reliability qualification test results.

Samples of the following part numbers will be available:

LPC2368FET100  
LPC2458FET180

LPC2460FET208  
LPC2468FET208  
LPC2470FET208

**Reason for Change**

Adding Copper wire is for supply assurance.

**Identification of Affected Products**

Top side marking

Product version is incremented from "D" to "E". See marking details in attached Self Qualification Report (SQR) document.

**Product Availability**

**Sample Information**

Samples are available from 14-Aug-2020

**Production**

Planned first shipment 28-Nov-2020

**Anticipated Impact on Form, Fit, Function, Reliability or Quality**

The top side marking, wire composition and mold compound are the only changes. No Impact to fit, function or reliability.

**Data Sheet Revision**

No impact to existing datasheet

**Disposition of Old Products**

Existing inventory will be shipped until depleted

**Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 02-Oct-2020.

**Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Tim Camenzind  
**Position** Quality Manager - LPC Microcontroller Products  
**e-mail address** tim.camenzind@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands



Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC2458FET180,551	935282454551	LPC2458FET180	32-BIT ARM7	SOT570-3	TFBGA180	RFS	MCUs
LPC2468FET208,551	935283234551	LPC2468FET208	32-bit ARM7	SOT950-1	TFBGA208	RFS	MCUs
LPC2478FET208,551	935284072551	LPC2478FET208	32-BIT ARM7	SOT950-1	TFBGA208	RFS	MCUs